

APPLICATION OF PULSED GLOW DISCHARGE TIME-OF-FLIGHT MASS SPECTROMETRY FOR ELEMENTAL ANALYSIS OF OPTICAL MATERIALS

#glow discharge #mass spectrometry
#fluorine #direct analysis #optical materials
#elemental analysis #depth profiling #hollow cathode
#KTP

A. Gubal¹, V. Chuchina¹, A. Ganeev¹, V. Yakobson²

¹Saint Petersburg State University, ²JSC "Research and Production Corporation S.I. Vavilova"
a.r.gubal@spbu.ru; a.r.gubal@mail.ru

Highlights

- A procedure of direct elemental analysis of the main components and dopants in optical materials based on pulsed GD TOF MS was developed.
- A new approach to the determination of high-ionization energy elements (O, F), which pose the greatest difficulties in the analysis of solid materials due to its high reactivity, volatility and high ionization energy, is proposed
- The possibility to control the stoichiometric composition and distribution of doping elements over the crystal volume (including depth profiling) is shown
- Pulsed GD MS allows for rapid and effective quality control of nonlinear optical crystals and to establish correlations between their growth conditions, composition and structure, and electrical and optical properties.

Introduction

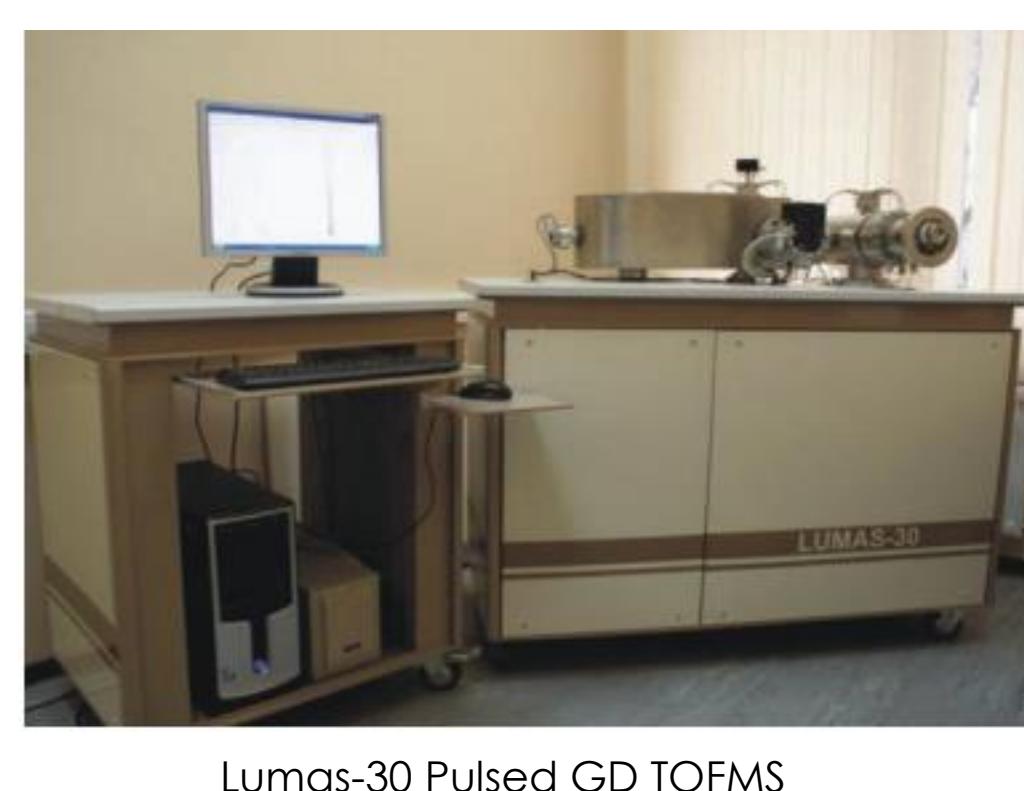


Crystal materials are widely used in laser optics. They are applied as second harmonic generation elements, electro-optical modulators or laser gain medium. Optical and nonlinear optical properties of these materials depend on their stoichiometric composition and distribution of main components and dopants in crystal volume. Therefore, a versatile analytical technique for the quality control of these material is essential.

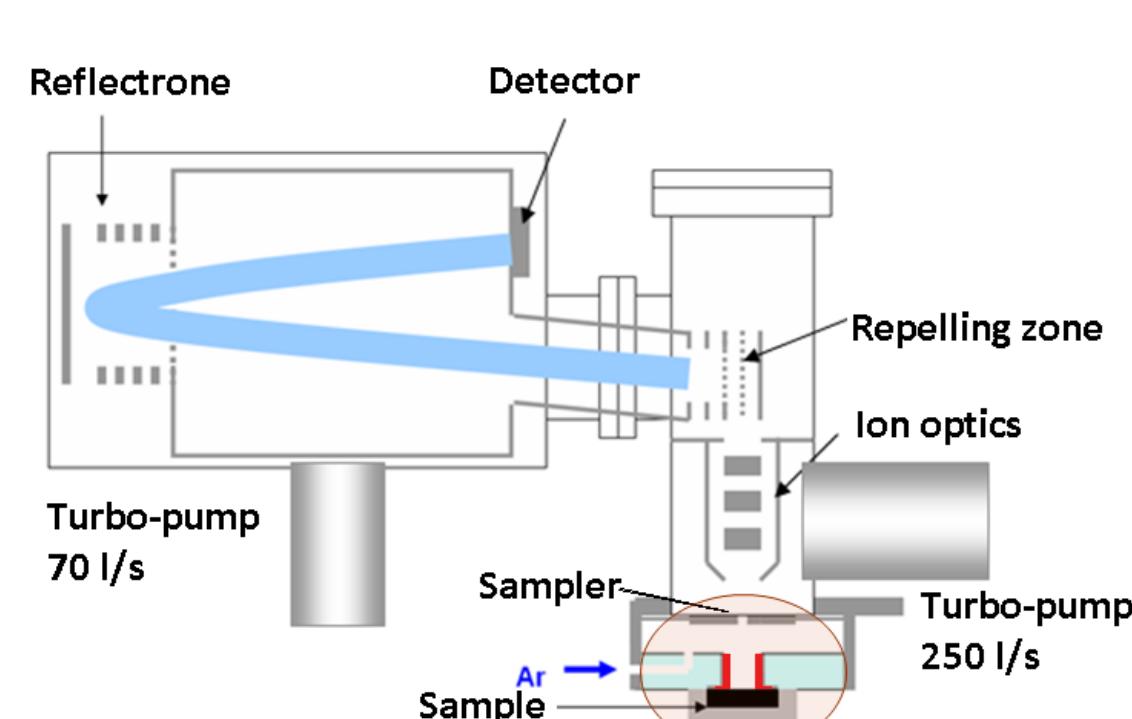
Currently, glow discharge mass spectrometry is widely and successfully used for the direct elemental analysis of various conducting and dielectric solids. The work considers perspectives of pulsed glow discharge mass spectrometry for elemental analysis of optical materials.

Materials and Methods

Instrumentation



Operating parameters	
Parameter	Value
Auxiliary cathode	Ta, Al
Sample aperture diameter	1.5 mm
Discharge pulse voltage, V	-900 to -1800
Discharge current	up to 3A
Pulse duration, μ s	2-5
Discharge frequency, kHz	1-4
Pressure, Pa	35-1150
Repelling pulse delay, μ s	1-300



Ion-optic scheme

Samples

KTP single crystals
(dielectric, used for second harmonic generation elements, electro-optical modulators):

KTiOPO₄
KTiOPO₄:KF (0.2 – 1.24 mass % F)
K_(1-x)Rb_xTIOPo4 (0.2 – 25 %)



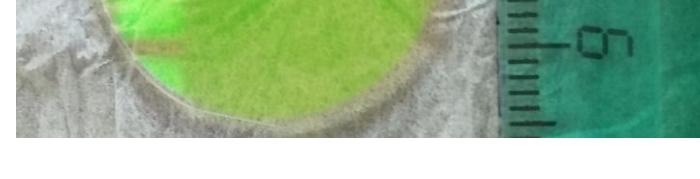
Laf₃SrF₂:Gd crystals
(dielectric, used as laser gain medium)

Laf₃SrF₂:Gd (0.01 – 16 mass % SrF₂, 0.05 mass % GdF₃)



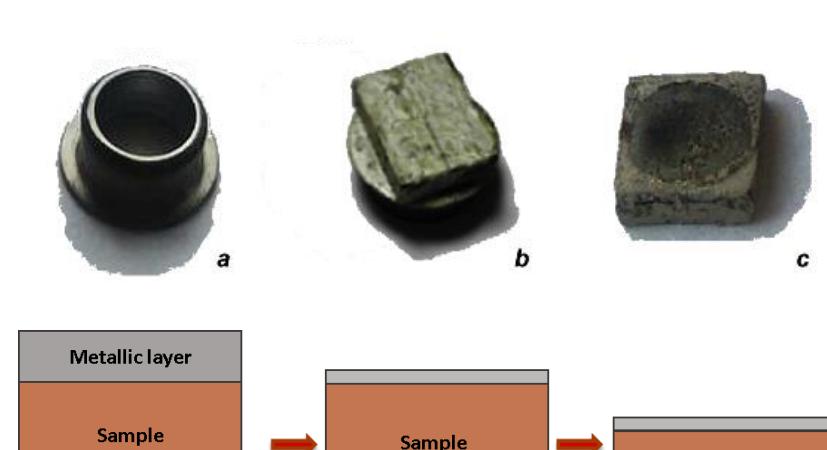
Coatings

350 nm Ni on silicon
Multilayer mirror coating
100 nm SiO₂-(200 nm TiO₂-200 nm SiO₂)x15 on glass



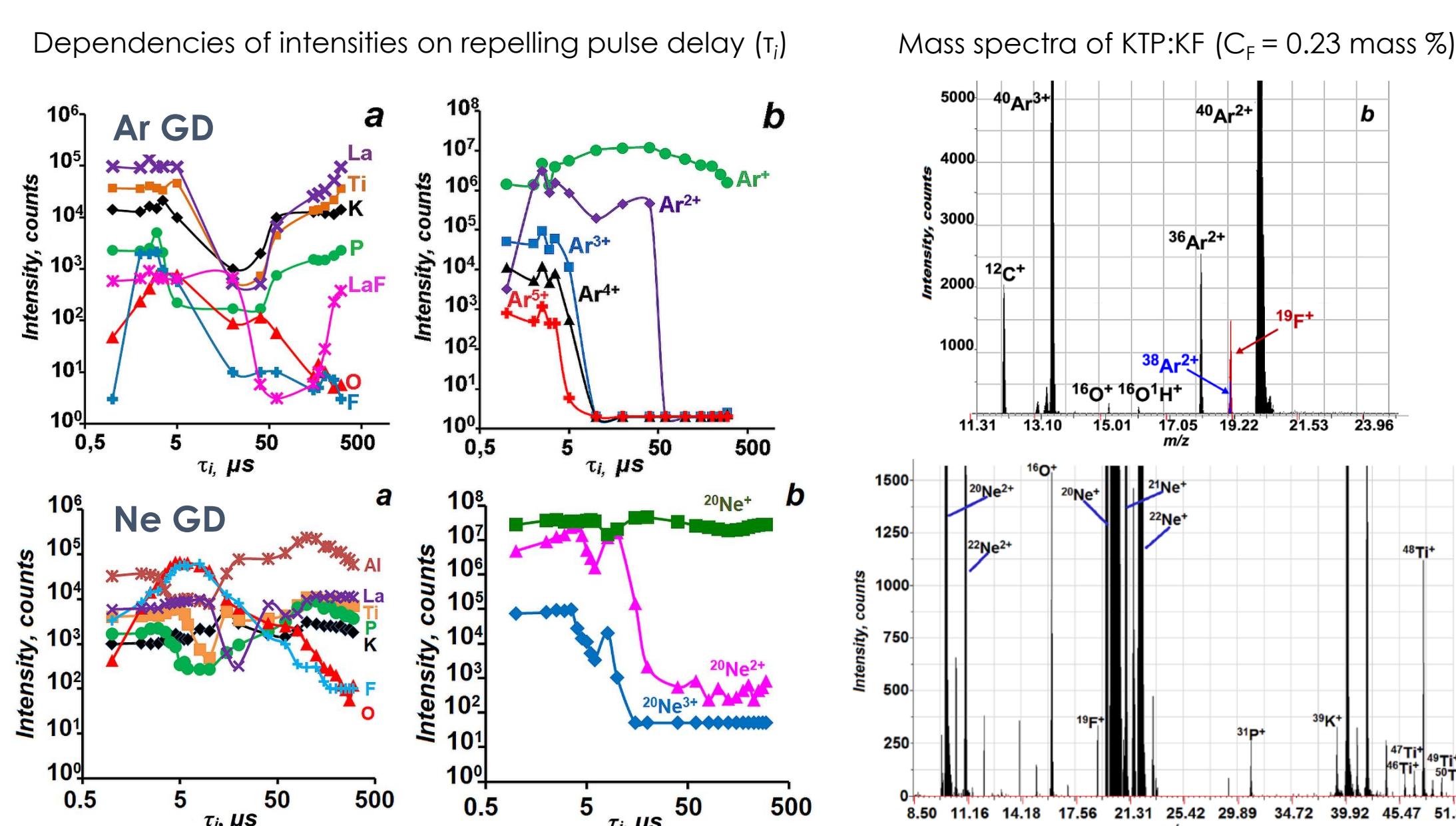
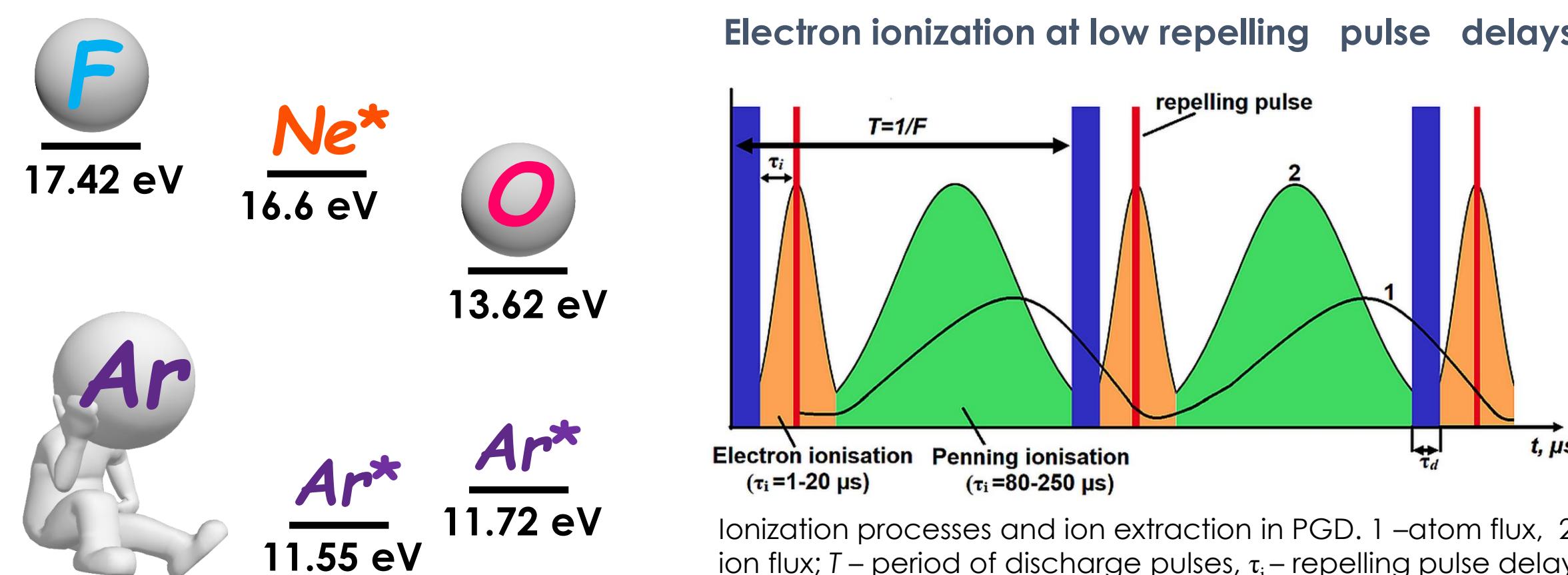
Sample preparation:

Covering with silver suspension in 2-propanol,
drying with a technical fan (150°C, 2 min)



For depth profiling vacuum deposition of silver layer (100-600 nm thickness) is used

High ionization energy elements



LaF₃SrF₂:Gd crystals

Powdering and pressing on aluminum foil table helps avoiding the signal instability

Sample	SrF ₂ , mass %	Putative	SEM EDX	GDMS
1	0.01	-	-	0.009±0.002
2	3.0	2.53±0.23	-	2.64±0.19
3	10.0	6.04±0.25	-	6.33±0.23
4	16.0	8.21±0.16	-	8.42±0.26

Continuous sputtering of samples with high fluorine content and ionic conductivity

F, O in KTP crystals

Parameter	Optimized parameters of O, F determination		
	Ar quant.	O quant.	Ne
Auxiliary cathode	Ta	Ta	Ta
Repelling pulse delay, μ s	3	4	4
Pulse duration, μ s	4	4	4
Discharge voltage, V	1300	1300	1800
Pressure, Pa	37	40	1150
Discharge frequency, kHz	3.2	3.2	3.2

Fluorine concentration of KTP:KF crystal and reference material SGD-1A (GDMS, SEM EDX)

Sample	C _F , mass %	C _F , mass %	C _F , mass %
	GDMS	SEM EDX	
KTP1	0.20 ^a	0.16±0.06	< 0.5
KTP2	0.22 ^a	0.23±0.07	< 0.5
KTP3	0.45 ^a	0.36±0.09	< 0.5
KTP4	0.45 ^a	0.39±0.11	< 0.5
KTP5	1.24 ^a	1.35±0.33	1.3±0.6
SGD-1A	0.12±0.01 ^b	0.11±0.04	< 0.5

^a – Putative value calculated from the crystallization charge,

^b – Certified value.

KTP elemental content (GDMS, GFA, SEM EDX)

Element	Stoichiometric, mass%	GDMS, mass%	GFA, mass%	SEM EDX, mass%
K	20.10	19.3±1.3	N.a.	16.4±1.3
Ti	24.12	(24.12) ^a	N.a.	18.6±0.9
P	15.58	16.5±1.7	N.a.	15.1±0.7
O	40.20	40.0±1.8	38.6±2.9	50.0±2.8

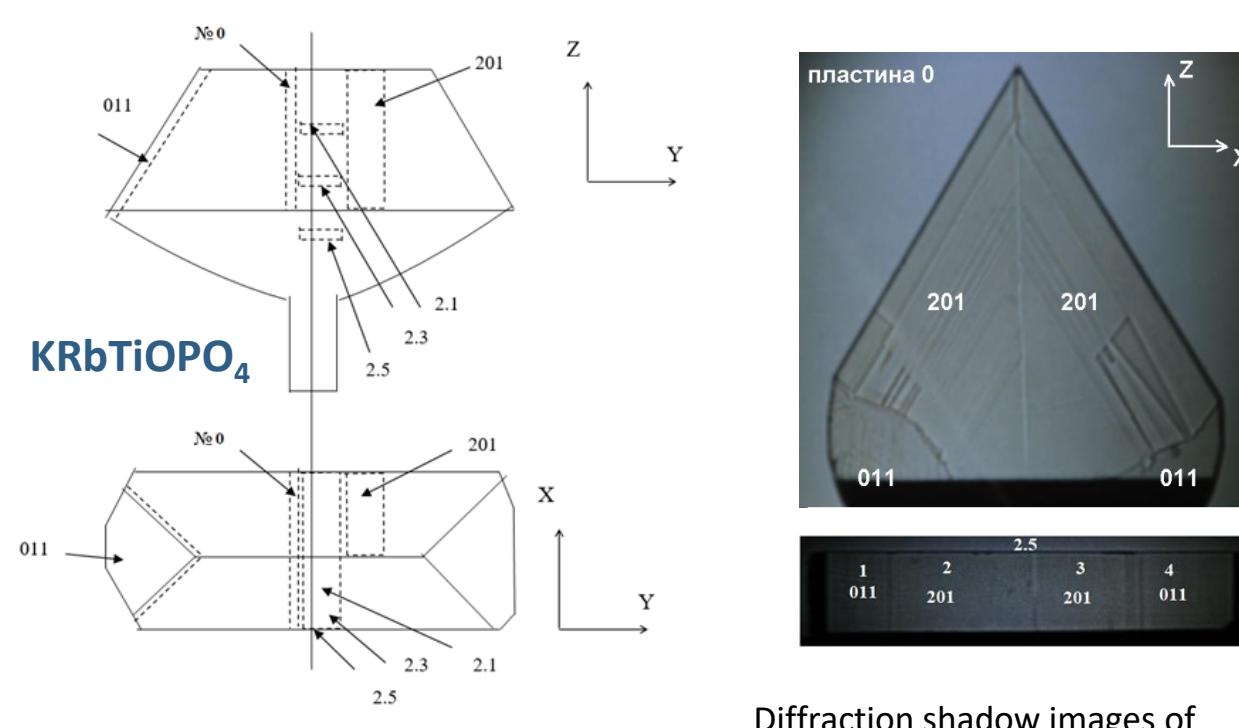
^a – Ti was used for internal standardisation

RSF and LoD values for Ar and Ne discharges

Element	Penning ionization	Electron ionization	
Ne	1.80±0.13	1.00	0.20±0.04
K	0.40±0.03	0.46±0.08	0.06±0.03
P	0.45±0.04	0.13±0.04	0.017±0.002
O	0.010±0.001	0.0710±0.0009	0.30±0.07
F	0.0060±0.0004	0.22±0.05	1.9±0.3

Element	LoD-Ar, mass %	LoD-Ne, mass %
K	0.002	0.008
P	0.001	0.01
O	0.001	0.0005
F	0.01	0.0002

Stoichiometry study



K and Rb content (at. %) in adjacent crystal growth faces

Crystall	Growth Face	GD MS Rb	SEM EDX Rb	GD MS K	SEM EDX K
97-05	(011)	0.022±0.001	-	11.20±0.11	11.26±0.20
31-11-07	(201)	0.052±0.003	-	12.50±0.06	-
31-34-14	(011)	0.067±0.004	0.2	13.12±0.07	0.03
31-36-14	(011)	0.044±0.005	1	13.04±0.12	0.8
94-06-17	(011)	0.066±0.004	5	12.14±0.06	0.63
H-01-19	(011)	0.020±0.002	5	12.17±0.17	3.0
31-71-97	(100)	0.35±0.02	10	11.93±0.04	1.25
31-72-97	(011)	0.28±0.01	20	11.59±0.07	2.50
31-73-97	(011)	0.28±0.01	25	11.54±0.18	7.9

Electrical resistivity of KRP samples with different Rb content

Crystall	Salt solvent	C_{Rb(RB+K)}, at.-%	R, 10¹¹ Ohm·cm (T=25°C)

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